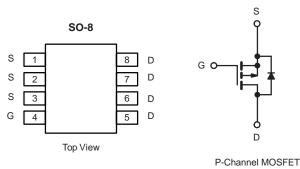


UM4407-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)			
- 30	0.011 at V _{GS} = - 10 V	- 11.6	22 nC			
- 30	0.012 at V _{GS} = - 4.5 V	- 10	22110			



FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- 100 % Rg Tested
- 100 % UIS Tested

APPLICATIONS

- Load Switches
- Notebook PCs
 - Desktop PCs



COMPLIANT HALOGEN

FREE Available

ABSOLUTE MAXIMUM RATINGS $T_A = 2$	25 °C, unless othe	erwise noted			
Parameter		Symbol	Limit	Uni	
Drain-Source Voltage		V _{DS}	- 30	V	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		- 11.6		
Continuous Drain Current (T - 150 °C)	T _C = 70 °C		- 10.5		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	- 8.7 ^{a, b}		
	T _A = 70 °C		- 7.7 ^{a, b}	•	
Pulsed Drain Current		I _{DM}	- 40	— A	
Ocationary Decis Diate Orange	T _C = 25 °C		- 4.6		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.0 ^{a, b}		
Avalanche Current		I _{AS}	- 20		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ	
	T _C = 25 °C		5.6		
Maria Dissination	T _C = 70 °C		3.6		
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W	
	T _A = 70 °C		1.6 ^{a, b}		
Operating Junction and Storage Temperature Range	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	39	50	°C/W		
Maximum Junction-to-Foot	Steady State	R _{thJF}	18	22	C/VV		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

c. Maximum under Steady State conditions is 85 °C/W. d. Based on $T_C = 25$ °C.

b. t = 10 s.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-,				1		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$			- 31		- mV/°C	
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J	I _D = - 250 μA		5.5			
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1.0		- 3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 25 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = - 30 V, V_{GS} = 0 V			- 1	μA	
Zero Gale voltage Drain Gurrent	1055	$V_{DS} = -30$ V, $V_{GS} = 0$ V, $T_{J} = 55$ °C			- 5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge$ - 10 V, V_{GS} = - 10 V	- 30			A	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 10 A		0.011		Ω	
Dialit-Source Off-State Resistance	(DS(on)	$V_{GS} = -4.5 \text{ V}, I_D = -7 \text{ A}$				52	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		23		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1960		pF	
Output Capacitance	C _{oss}	V_{DS} = - 15 V, V_{GS} = 0 V, f = 1 MHz		380			
Reverse Transfer Capacitance	C _{rss}			325			
Total Gate Charge	Qg	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 10 A	43	65			
				22	33	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		6			
Gate-Drain Charge	Q _{gd}			11			
Gate Resistance	R _g	f = 1 MHz	0.3	1.3	2.5	Ω	
Turn-On Delay Time	t _{d(on)}			11	22	_	
Rise Time	t _r	V_{DD} = - 15 V, R _L = 3 Ω		13	25		
Turn-Off DelayTime	t _{d(off)}	$\text{I}_\text{D}\cong$ - 5 A, V_GEN = - 10 V, R_g = 1 Ω		32	50		
Fall Time	t _f			9	18	ns	
Turn-On Delay Time	t _{d(on)}			44	70	-	
Rise Time	t _r	V_{DD} = - 15 V, R _L = 3 Ω		100	160		
Turn-Off DelayTime	t _{d(off)}	$\rm I_D \cong$ - 5 A, $\rm V_{GEN}$ = - 4.5 V, $\rm R_g$ = 1 Ω		28	50		
Fall Time	t _f			15	30		
Drain-Source Body Diode Characterist	ics						
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 4.6	А	
Pulse Diode Forward Current	I _{SM}				- 50		
Body Diode Voltage	V _{SD}	I _S = - 2 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			28	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			20	40	nC	
Reverse Recovery Fall Time	$I_{r} = -2 \text{ A} \cdot \text{d}/\text{d}t = 100 \text{ A/us} \cdot I_{r} = 25 \text{ °C}$			13			
Reverse Recovery Rise Time	t _b			15		ns	

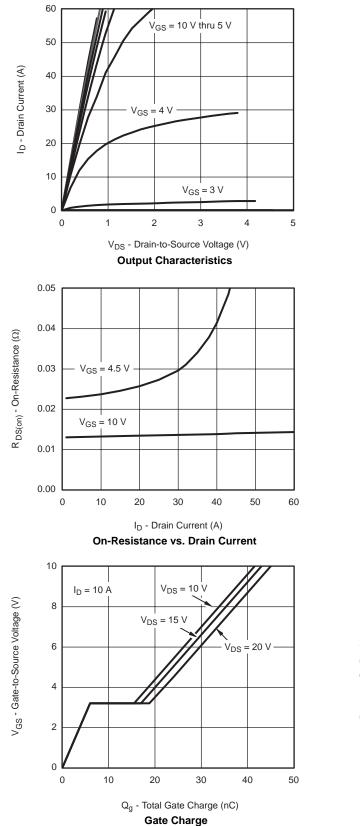
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

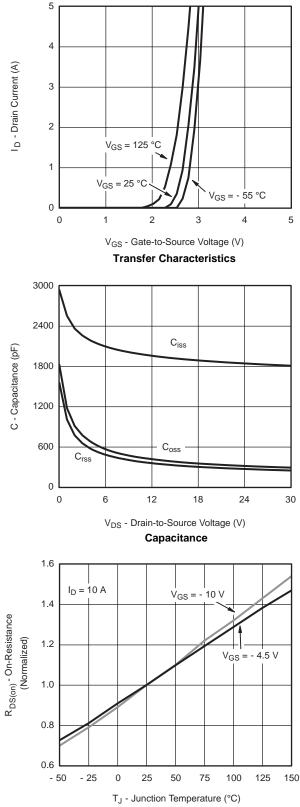
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

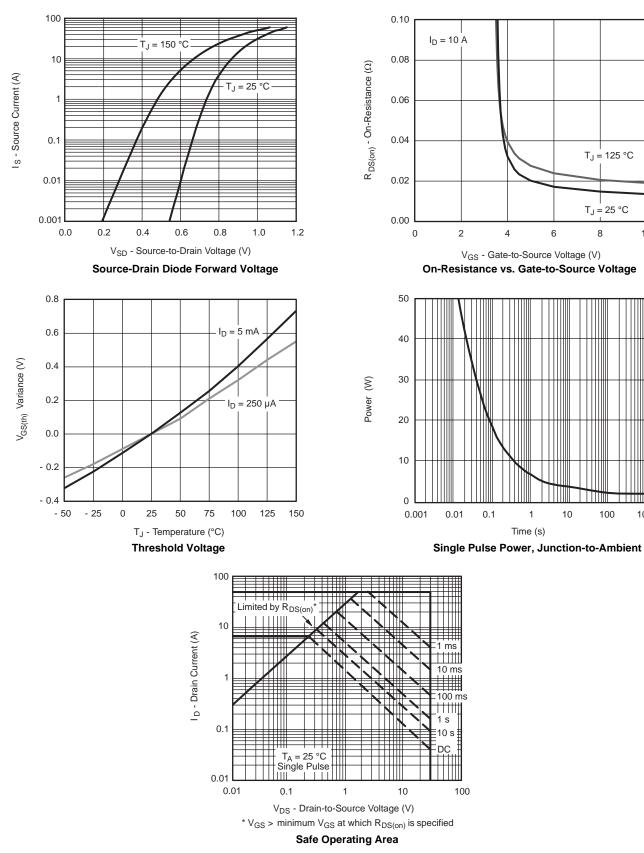


On-Resistance vs. Junction Temperature



10

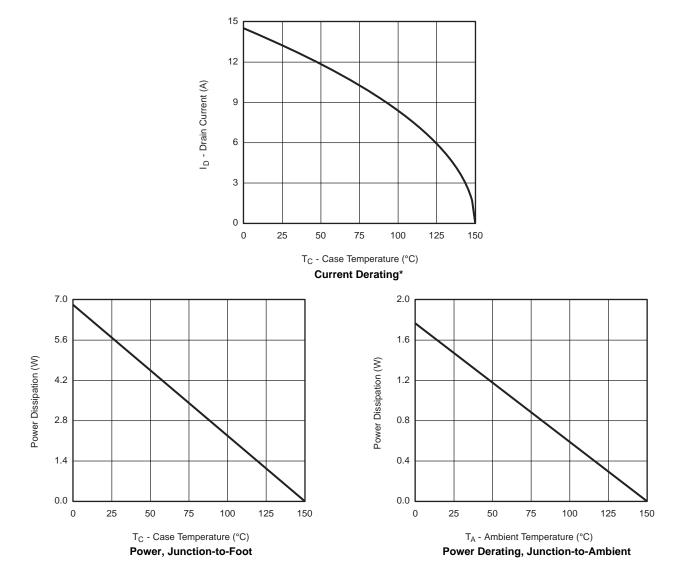
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



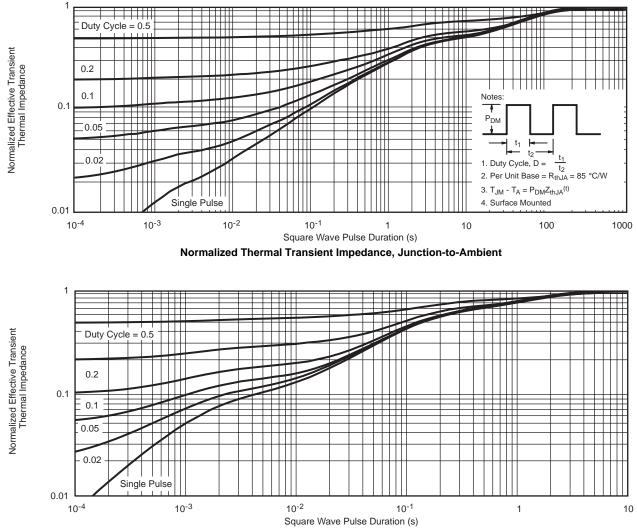
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

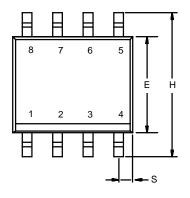


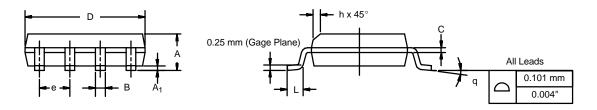
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

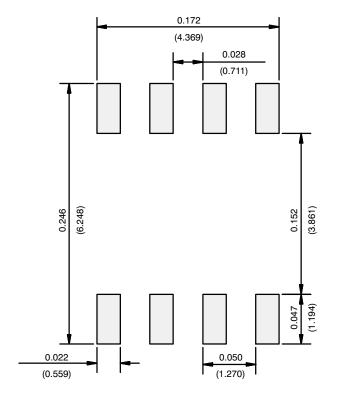




	MILLIM	IETERS	INC	HES		
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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